	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	80	(die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (insulative or dielective) and 257/666 and (recess or opening or hole or via) and (conductor or metal$ or wiring) and package	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2001/10/15 14:11
2	BRS	26	(die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (insulative or dielective) and 257/704 and (recess or opening or hole or via) and (conductor or metal$ or wiring) and package	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2001/10/15 14:23
3	BRS	4	(die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (insulative or dielective) and 257/763 and (recess or opening or hole or via) and (conductor or metal$ or wiring) and package	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2001/10/15 14:42
4	BRS	5	(die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (insulative or dielective) and 257/766 and (recess or opening or hole or via) and (conductor or metal$ or wiring) and package	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2001/10/15 14:53
5	BRS	3	(die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (insulative or dielective) and 257/762 and (recess or opening or hole or via) and (conductor or metal$ or wiring) and package	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2001/10/15 14:56

	Type	Hits	Search Text	DBs	Time Stamp
6	BRS	21	(die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (insulative or dielective) and 257/687 and (recess or opening or hole or via) and (conductor or metal$ or wiring) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/10/15 15:04
7	BRS	25	(die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (insulative or dielective) and 257/684 and (recess or opening or hole or via) and (conductor or metal$ or wiring) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/10/15 15:07
8	BRS	41	(die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (insulative or dielective) and 257/676 and (recess or opening or hole or via) and (conductor or metal$ or wiring) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/10/15 15:11
9	BRS	14	(die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (insulative or dielective) and 257/673 and (recess or opening or hole or via) and (conductor or metal$ or wiring) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/10/15 15:18
10	BRS	9	(die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (insulative or dielective) and 257/667 and (recess or opening or hole or via) and (conductor or metal$ or wiring) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/10/15 15:20

	Type	Hits	Search Text	DBs
1	BRS	666	(die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (insulative or dielective) and (recess or opening or hole or via) and (conductor or metal$ or wiring) and package	USPAT; JPO
2	BRS	25	(die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (insulative or dielective) and (recess or opening or hole or via) and (conductor or metal$ or wiring) and package and (Cu or copper) and (Ti or titanium) and (Cr or chrome)	USPAT; JPO
3	BRS	10	((die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (insulative or dielective) and (recess or opening or hole or via) and (conductor or metal$ or wiring) and package) and (6130474.pn. or 6110650.pn. or 5986885.pn. or 5977633.pn. or 5904495.pn. or 5773884.pn. or 5633533.pn. or 5095402.pn. or 5045914.pn. or 4649415.pn.)	USPAT; JPO
4	BRS	10	((die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (insulative or dielective) and (recess or opening or hole or via) and (conductor or metal$ or wiring) and package) and (6130474.pn. or 6110650.pn. or 5986885.pn. or 5977633.pn. or 5907769.pn. or 5773884.pn. or 5633533.pn. or 5095402.pn. or 5045914.pn. or 4649415.pn.)	USPAT; JPO

	Type	Hits	Search Text	DBs
5	BRS	9	(die or chip or semiconduct$) and (bump or ball) and (pad or connection or terminal) and (recess or opening or hole or via) and (Cu or copper) adj layer and (Ti or titanium) adj layer and (Cr or chrome) adj layer	USPAT; JPO
6	BRS	0	(multi$ adj layer) near ((Cu or copper) adj layer and (Ti or titanium) adj layer and (Cr or chrome) adj layer)	USPAT; JPO
7	BRS	8	(multi$ adj layer) and ((Cu or copper) adj layer and (Ti or titanium) adj layer and (Cr or chrome) adj layer)	USPAT; JPO
8	BRS	39	((Cu or copper) adj layer and (Ti or titanium) adj layer and (Cr or chrome) adj layer)	USPAT; JPO
9	BRS	31	((Cu or copper) adj layer and (Ti or titanium) adj layer and (Cr or chrome) adj layer) not ((multi$ adj layer) and ((Cu or copper) adj layer and (Ti or titanium) adj layer and (Cr or chrome) adj layer))	USPAT; JPO
10	BRS	8	5986885.pn. or 5977633.pn. or 5633533.pn. or 5907769.pn. or 5095402.pn. or 4649415.pn. or 59145537.pn. or 58197857.pn.	USPAT; JPO